SPECIFICATIONS

客户:

CUSTOMER:	
产品名称:	
DESCRIPTION:	Bipolar antenna
客户型号:	
CUSTOMER PART	No:
产品型号:	
OUR MODEL NO:	PBX3216MC02
日期:	
DATE:	

确认签字,盖章后请返回承认书一份

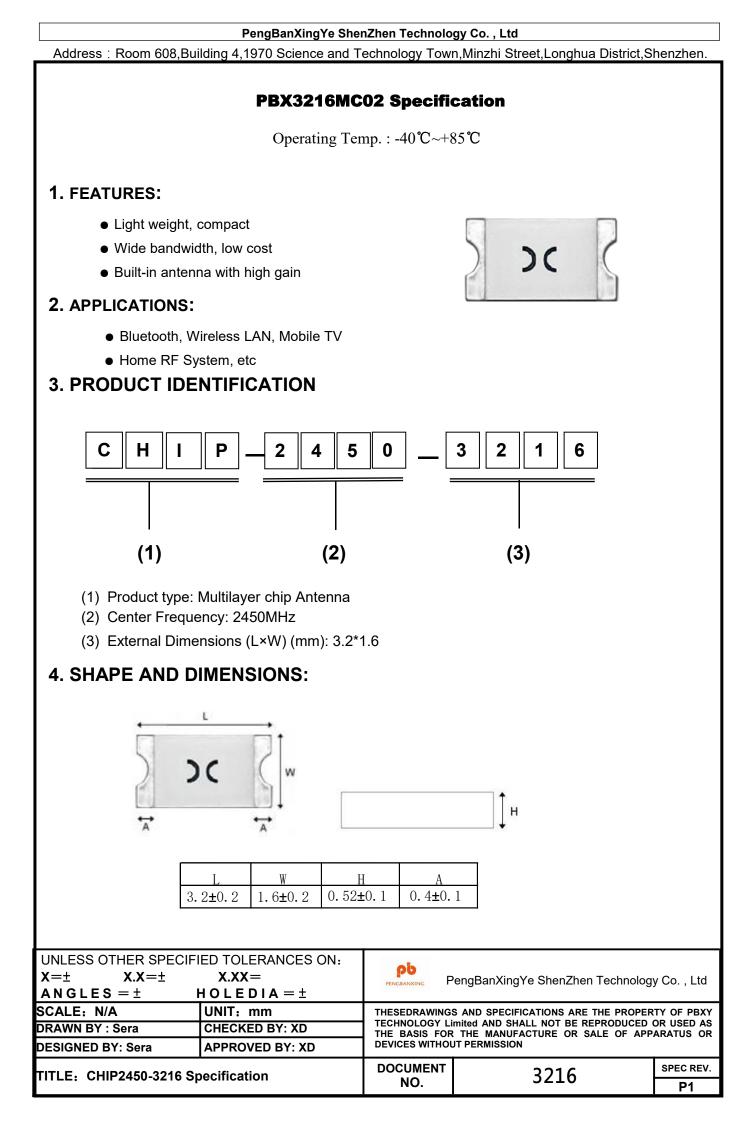
PLEASE RETURN TO US ONE COPY OF "SPECIFICATION FOR APPROVAL"

WITH YOUR APPROVED SIGNATURES

Approved	LiuFei	Audit	LiuFei	Making	LiuXiaoMei
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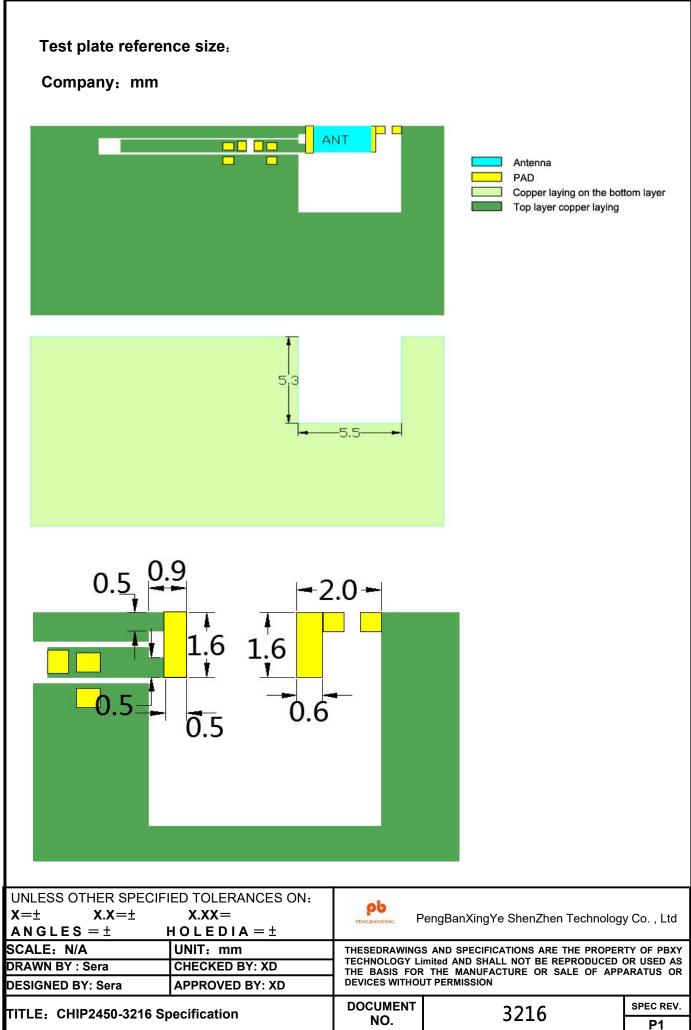
Customer Acknowledges Signature	
Date	

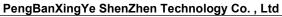
UNLESS OTHER SPECIF $X=\pm$ $X.X=\pm$ ANGLES = \pm	IED TOLERANCES ON: X.XX= HOLEDIA=±	PengBanXingYe ShenZhen Technology Co. ,			
SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PBX			
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DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION			
TITLE: CHIP2450-3216 Specification		DOCUMENT	3216	SPEC REV.	
		NO.	NO. 5210		



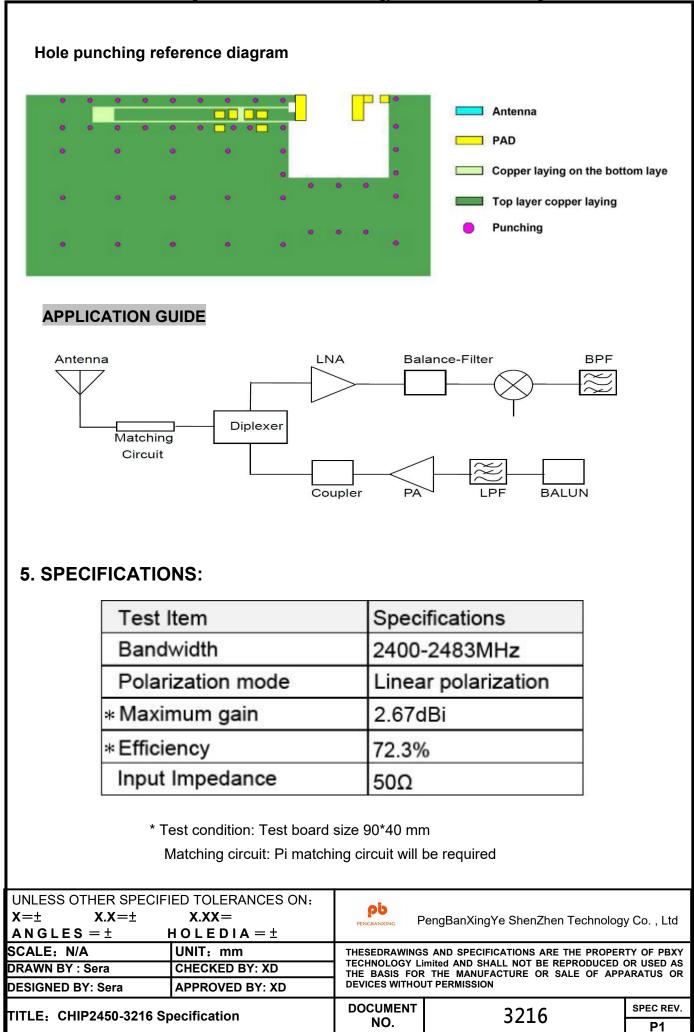






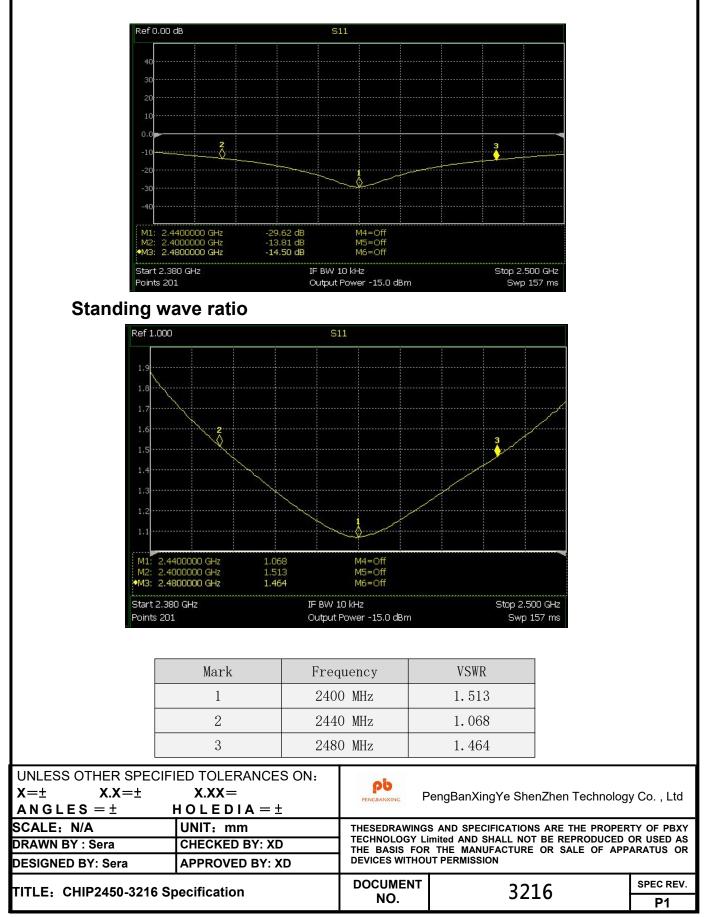


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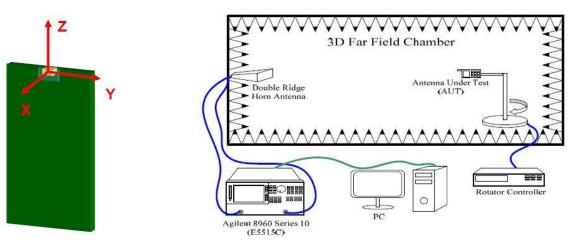
6. Electrical Characteristics :

Return loss

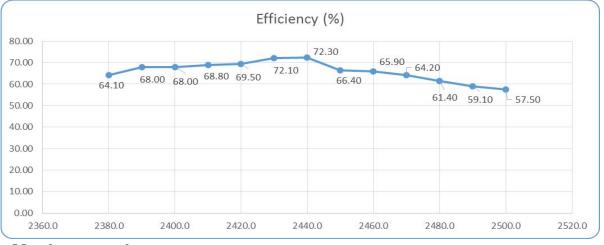


Radiation Pattern

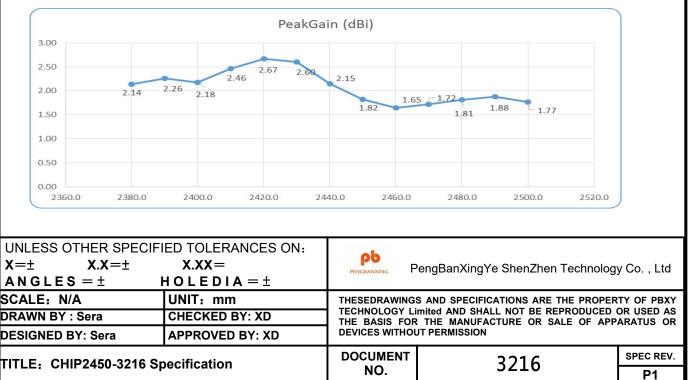
The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.

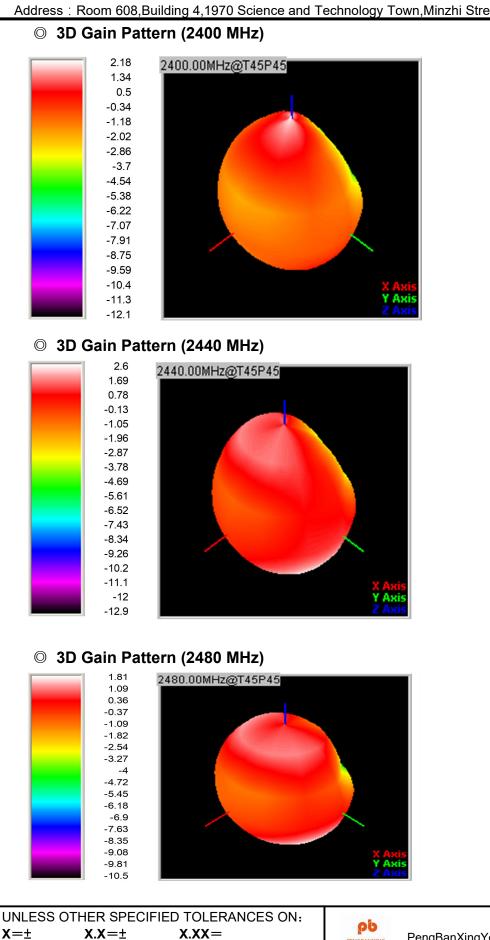


O Efficiency









PENGBANXING	PengBanXingYe ShenZhen Technology Co. , Ltd

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TITLE: CHIP2450-5216 Specification		NO.	5210	P1	

7. Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at -40° C $\pm 5^{\circ}$ C, 2. Convert to $\pm 105^{\circ}$ C (5 minutes) 3. 30 ± 3 minutes at $\pm 105^{\circ}$ C $\pm 5^{\circ}$ C, 4. Convert to -40° C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: 85±5° C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : 260±5℃ 2. Bathing time: 10±1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of 245 ± 5 °C for 3 ± 1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0 \sim 30^{\circ}$ C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

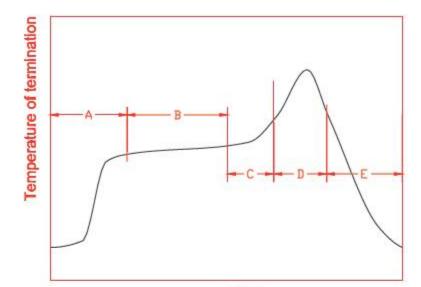
The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40 $^\circ\!\mathrm{C}$ to +105 $^\circ\!\mathrm{C}$.

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8. Recommended Reflow Soldering



		Time	
A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
В	Preheating	140℃ to 160℃	60s to 120s
С	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200℃ to 100℃	1℃/s ~ 4℃/s

*reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

- (a) The tip temperature must be less than 350 $^\circ\,$ C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

Note that excess of soldering volume will easily get crack the body of this product.

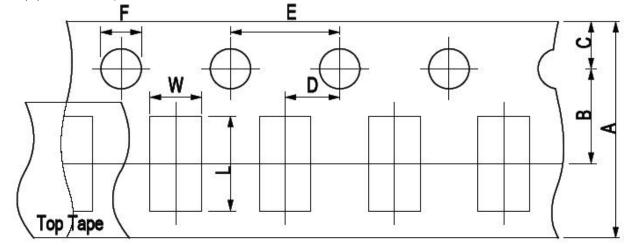
UNLESS OTHER SPECIFIED TOLERANCES ON: $X=\pm$ $X.X=\pm$ $ANGLES=\pm$ $HOLEDIA=\pm$		PengBanXingYe ShenZhen Technology Co. ,			
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9. Taping Package and Label Marking: (unit: mm)

- (1) Quantity/Reel: 5000pcs/Reel
- (2) Carrier tape dimensions



Туре	А	В	С	D	E	F	L	W
2450-21	8.00±0.3	3.50 \pm 0.05	1.75 \pm 0.1	2.00 ± 0.05	4.00±0.1	1.50±0.1	2.30 \pm 0.1	1.55 ± 0.1

(3) Taping reel dimensions

